

TH 930

Silicone Thermal Putty

Description

TH 930 is a non cured one-part thermal conductive interface material based on silicone resins. It is designed for good thermal conduction with high electrical insulation. This silicone thermal putty is easy to handle on electronic parts and devices.

Applications

1. Thermal conductive interface material for electronic parts and devices.

Guidelines for Use

1. Wear rubber gloves when handling this silicone thermal putty.
2. Pick up some of the silicone thermal putty from the container using hand.
3. Work the silicone thermal putty around electronic part and circuit by hand.
4. Wipe off any excess putty with a piece of dry cloth or tissues. Further cleaning of residues may be achieved by wiping with cloth wetted with iso-propanol.

Properties

Property	Test Method	Unit	Typical Value
Chemical type		-	Silicone
Appearance	Pen 10	-	White
Mix ratio, by weight		-	One component
Shelf life, 25°C	Pen 26	Month	12
Viscosity, Brookfield RVT	Pen 11	cP	Putty
Thermal conductivity	ISO/DIS 22007	W/mK	2.5
Hardness	Pen 29	Shore 00	50

Storage

Store this silicone thermal putty in air tight container, cool, dark place (temperature range from 20°C to 30°C) to prolong shelf life. Prevent moisture condition.

Packaging

- Putty form in 1kg or 5kg pail
- Will provide customized packaging if required

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

Penchem Technologies Sdn Bhd
(767120-A), 1015, Jalan Perindustrian Bukit Minyak 7, 14100 Penang, Malaysia
T: +604-501 5976, 77, 78
F: +604-501 5979
E: enquiry@penchem.com
W: www.penchem.com

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